

Examiner:

A. Chambliss

Art Unit: 2814

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants

K. TATSUMI et al.

Serial No.

09/254,118

Filed

May 19, 1999

For

METHOD OF PARTIALLY PLATING SUBSTRATE FOR

ELECTRONIC DEVICES

Assistant Commissioner

for Patents

Washington, D.C. 20231

TRANSMITTAL LETTER

SIR:

Transmitted herewith is an Amendment/Response in the above-identified patent application.

[X] No additional fee is required.

The fee has been calculated as shown below.

			SMALL EN	PITY	OTH SMA	ER THAN A
CLAIMS REMAINING AFTER <u>AMENDMEN</u> T	HIGHEST NO PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDIT. <u>OR</u> FEE	RATE	ADDIT. FEE
TOTAL 9 M	IINUS 20	= 0	x6 =	\$	x18 =	\$ 0
	-	= 0	x18 =	\$	x80 =	\$ 0.00
[]FIRST PRESE	NTATION OF M	ULTIPLE	x60 =	\$	x270 =	\$ 0.00
DEP. CLAIM TOTAL						
		ADDIT.	FEE	\$OR		\$0.00

[X] The Commissioner is hereby authorized to charge fees under 37 CFR 1.16 and 1.17 which may be required to Deposit Account 11-0600. A duplicate of this paper is enclosed.

[X] A petition for a three (3) month extension of time and Deposit Account authorization to cover the extension fee are enclosed.

Respectfully submitted,

KENYON & KENYON

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on August 7, 2001

John J. Kelly, Jr. Reg. No. 29,182

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Reg. No. 29,182

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